

Wiring, Printed - Component

COMPANY
MULTI CIRCUIT BOARDS LTD

Business Centres
 Holyrood Close
 Poole, BH17 7FJ United Kingdom

E198312

Type	Cond Width			Max Report				Max							
	Min		Cond	SS/	Area	Date	Surface	Assembly		Solder	Solder	Oper	Meets	C	
	Min	Edge	Thk	DS/	Diam	After	Mount	Process	Process	Limits	Temp	Flame	UL796	T	
				2022-01-01				Temp							
Type	mm	mm	mic	DSO	mm	01-01	Technology	°C	Cycles	°C	sec	°C	Class	DSR	I
Multilayer printed wiring boards															
ML01	0.05	0.1	5 Int:102	DS	50.8	No	-	-	-	288	20	130	V-0	All	3
ML02	0.076	0.076	16.5 Int:70	DS	21.4	No	-	-	-	288	10	130	V-0	All	3
ML03	0.08	0.05	16.5 Int:70	DS	21.4	No	-	-	-	288	10	130	V-0	All	3
ML03_MEG	0.1	0.1	16.5 Int:70	DS	21.4	No	-	-	-	288	10	130	V-0	All	3
ML03_PLA	0.08	0.08	16.5 Int:70	DS	21.4	No	-	-	-	288	10	130	V-0	All	1
ML05	0.1	0.1	12 Int:70	DS	76.2	No	-	-	-	288	20	130	V-0	All	*
ML06	0.075	0.10	17 Int:68	DS	38.1	No	-	-	-	280	20	130	V-0	All	*
ML07	0.1	0.25	16.5 Int:105	DS	25.4	No	-	-	-	280	5	130	V-0	All	*
ML08	0.075	0.075	17 Int:204	DS	76.2	No	-	-	-	288	20	130	V-0	All	*
ML09_MEG	0.08	0.08	17 Int:70	DS	50.8	No	-	-	-	288	20	130	V-0	All	3
ML09_PLA	0.08	0.12	17 Int:34	DS	50.8	No	-	-	-	280	20	130	V-0	All	0

ML09_ROG	0.125	0.375	17 Int:70	DS	50.8	No	-	-	-	260	20	105	V-0	-	*
ML11	0.1	0.1	17 Int:34	DS	50.8	No	-	-	-	280	20	130	V-0	All	*
ML11_ROG	0.14	0.14	18 Int:35	DS	50.8	No	-	-	-	288	20	130	V-0	All	*
ML12	0.10	0.10	17 Int:136	DS	76.2	No	-	-	-	288	10	130	V-0	All	*

Single Layer Metal Base Printed Wiring Boards

SLMC05	0.2	0.4	17	SS	25.4	No	-	-	-	288	30	130	V-0	All	0
SLMC08	0.18	0.33	34	SS	50.8	No	-	-	-	260	20	125	V-0	-	*
SLMC11	0.10	0.10	18	SS	50.8	No	-	-	-	288	20	130	V-0	All	0

Single layer printed wiring boards

SL01	0.05	0.1	5	DS	50.8	No	-	-	-	288	20	130	V-0	All	*
SL02	0.076	0.076	17	DS	21.4	No	-	-	-	288	10	130	V-0	All	3
SL03	0.08	0.05	16.5	DS	21.4	No	-	-	-	288	10	130	V-0	▲	*
SL03_MEG	0.1	0.1	16.5	DS	21.4	No	-	-	-	288	10	130	V-0	All	3
SL03_PLA	0.08	0.08	16.5	DS	21.4	No	-	-	-	288	10	130	V-0	All	1
SL05	0.1	0.1	12	DS	76.2	No	-	-	-	288	20	130	V-0	All	*
SL06	0.075	0.10	17	DS	38.1	No	-	-	-	280	20	130	V-0	All	*
SL07	0.1	0.25	16.5	DS	25.5	No	-	-	-	280	5	130	V-0	All	*
SL08	0.075	0.075	17	DS	76.2	No	-	-	-	288	20	130	V-0	All	*
SL09_PLA	0.08	0.12	17	DS	76.2	No	-	-	-	280	20	130	V-0	All	0
SL09_ROG	0.1	0.16	17	DS	50.8	No	-	-	-	260	20	105	V-0	All	*
SL11	0.1	0.1	17	DS	50.8	No	-	-	-	280	20	130	V-0	All	*
SL11_ROG	0.14	0.14	18	DS	50.8	No	-	-	-	288	20	130	V-0	All	*
SL12	0.10	0.30	17	DS	76.2	No	-	-	-	288	10	130	V-0	All	*

* - CTI marking is optional and may be marked on the printed wiring board.

- when the external Cu thickness is 136 mic, Min. conductor width is 0.31 mm and Min. Edge conductor width is 0.33 mm.

Marking: Company name or trademark "E198312" or file number and type designation. May be followed by a suffix to denote factory identification or flammability classification..

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